





NPN PLASTIC POWER TRANSISTORS

CSC2690 CSC2690A



TO-126 Leaded Plastic Package RoHS compliant

TO-126

FEATURES:

- 1. Complementary PNP Transistors CSA1220, CSA1220A
- 2. This product is available in AEC-Q101 Compliant and PPAP Capable also.

Note: For AEC-Q101 compliant products, please use suffix -AQ in the part number while ordering.

APPLICATIONS: Audio frequency, High Frequency and Power Amplifier

ABSOLUTE MAXIMUM RATINGS (Ta = 25 °C Unless otherwise specified)

PARAMETER	SYMBOL	CSC 2690	CSC 2690A	UNIT
Collector -Base Voltage (open emitter)	V_{CBO}	120	160	V
Collector -Emitter Voltage(open base)	V_{CEO}	120	160	V
Emitter Base Voltage(open collector)	V_{EBO}	5	5.0	V
Collector current (DC)	I _C	1	.2	Α
Collector Current (Pulse) ¹	I _C	2	5	Α
Base current (DC)	l _B	0	.3	Α
Total power dissipation up to T _A = 25°C	Б	1	.2	W
Total power dissipation up to T _C = 25°C	P _{tot}	2	20	
Junction Temperature	T _j	1	50	°C
Storage Temperature Range	T _{stg}	-65 to	o +150	°C







ELECTRICAL CHARACTERISTICS (T_A = 25°C; unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITION		CSC 2690	CSC 2690A	Unit
Collector cutoff current	I _{CBO}	$I_E = 0; V_{CB} = 120V$	Max	1	.0	μΑ
Emitter Cut off Current	I _{EBO}	$I_{\rm C}$ = 0; $V_{\rm EB}$ = 3V	Max	1.0		μA
	V_{CEO}	$I_{\rm C} = 1 {\rm mA}; I_{\rm B} = 0$	Max	120	160	V
Breakdown voltages	V_{CBO}	$I_{\rm C} = 1 {\rm mA}; I_{\rm E} = 0$	Max	120	160	V
	V_{EBO} $I_E = 1mA; I_C = 0$	Max	5.0		V	
Seturation voltage	V _{CEsat} 1	$I_{c} = 1A$: $I_{b} = 0.2A$	Max	0	.7	V
Saturation voltage	V _{BE(sat)} 1		Max	1.3		V
D.C. current gain	h 1	I_{C} =5mA, V_{CE} =5V I_{C} =0.3mA, V_{CE} =5V I_{C}	Min	Ç	35	
D.C. current gain	h _{FE} 1		$I_{\text{C}} = 0.3 \text{mA}, V_{\text{CE}} = 5 \text{V}^2$	$I_{\rm C}$ =0.3mA, $V_{\rm CE}$ =5 V^2 60 ~ 320		~ 320
Output capacitance	C_{ob}	V_{CB} =10V, I_{E} =0	Тур	1	9	pF
Transition frequency	f_T	$I_C = 0.2A; V_{CE} = 5V$	Тур	1	55	MHz

Note:

1. Pulse test tp ≤300µs, Duty cycle ≤2%



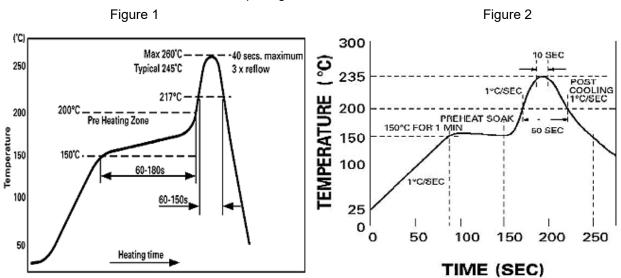


Recommended Reflow Solder Profiles

The recommended reflow solder profiles for Pb and Pb-free devices are shown below.

Figure 1 shows the recommended solder profile for devices that have Pb-free terminal plating, and where a Pb-free solder is used.

Figure 2 shows the recommended solder profile for devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with a leaded solder.



Reflow profiles in tabular form

Profile Feature	Sn-Pb System	Pb-Free System
Average Ramp-Up Rate	~3°C/second	~3°C/second
Preheat - Temperature Range - Time	150-170°C 60-180 seconds	150-200°C 60-180 seconds
Time maintained above: – Temperature – Tim	200°C 30-50 seconds	217°C 60-150 seconds
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	40 seconds
Ramp-Down Rate	3°C/second max.	6°C/second max



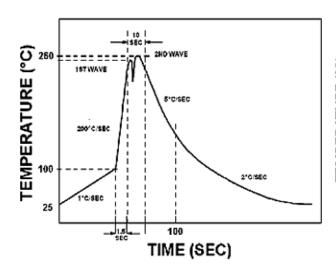


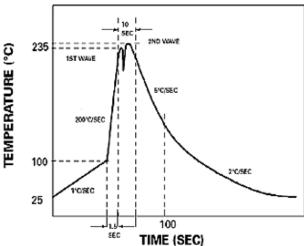


Recommended Wave Solder Profiles

The Recommended solder Profile For Devices with Pb-free terminal plating where a Pb-free solder is used

The Recommended solder Profile For Devices with Pb-free terminal plating used with leaded solder, or for devices with leaded terminal plating used with leaded solder





Wave Profiles in Tabular Form

Profile Feature	Sn-Pb System	Pb-free System
Average Ramp-Up Rate	~200°C/second	~200°C/second
Heating rate during preheat	Typical 1-2, Max 4°C/sec	Typical 1-2, Max 4°C/Sec
Final preheat Temperature	Within 125°C of Solder Temp	Within 125°C of Solder Temp
Peak Temperature	235°C	260°C max.
Time within +0 -5°C of actual Peak	10 seconds	10 seconds
Ramp-Down Rate	5°C/second max.	5°C/second max.







TYPICAL CHARACTERISTICS CURVES Fig. 1. Static Characteristic

Fig. 3. DC Current Gain

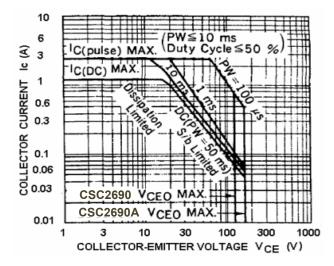
Fig. 3. DC Current Gain

VCE = 5.0 V3

T c = 25° C

OLLECTOR CURRENT Ic (A)

Fig. 2. Safe Operating Area



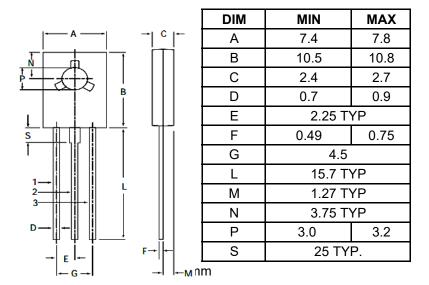






Package Details

TO-126 Leaded Plastic Package



PIN CONFIGURATION

- 1. Emitter
- 2. Collector
- 3. Base







Recommended Product Storage Environment for Discrete Semiconductor Devices

This storage environment assumes that the Diodes and transistors are packed properly inside the original packing supplied by CDIL.

- · Temperature 5 °C to 30 °C
- · Humidity between 40 to 70 %RH
- · Air should be clean.
- · Avoid harmful gas or dust.
- · Avoid outdoor exposure or storage in areas subject to rain or water spraying .
- · Avoid storage in areas subject to corrosive gas or dust. Product shall not be stored in areas exposed to direct sunlight.
- · Avoid rapid change of temperature.
- · Avoid condensation.
- · Mechanical stress such as vibration and impact shall be avoided.
- · The product shall not be placed directly on the floor.
- The product shall be stored on a plane area. They should not be turned upside down. They should not be placed against the wall.

Shelf Life of CDIL Products

The shelf life of products is the period from product manufacture to shipment to customers. The product can be unconditionally shipped within this period. The period is defined as 2 years.

If products are stored longer than the shelf life of 2 years the products shall be subjected to quality check as per CDIL quality procedure.

The products are further warranted for another one year after the date of shipment subject to the above conditions in CDIL original packing.

Floor Life of CDIL Products and MSL Level

When the products are opened from the original packing, the floor life will start. For this, the following JEDEC table may be referred:

JEDEC MSL Level		
Level	Time	Condition
1	Unlimited	≤30 °C / 85% RH
2	1 Year	≤30 °C / 60% RH
2a	4 Weeks	≤30 °C / 60% RH
3	168 Hours	≤30 °C / 60% RH
4	72 Hours	≤30 °C / 60% RH
5	48 Hours	≤30 °C / 60% RH
5a	24 Hours	≤30 °C / 60% RH
6	Time on Label(TOL)	≤30 °C / 60% RH







Customer Notes

Component Disposal Instructions

- 1. CDIL Semiconductor Devices are RoHS compliant, customers are requested to please dispose as per prevailing Environmental Legislation of their Country.
- 2. In Europe, please dispose as per EU Directive 2002/96/EC on Waste Electrical and Electronic Equipment (WEEE).

Disclaimer

The product information and the selection guides facilitate selection of the Coil's Semiconductor Device(s) best suited for application in your product(s) as per your requirement. It is recommended that you completely review our Data Sheet(s) so as to confirm that the Device(s) meet functionality parameters for your application. The information furnished in the Data Sheet and on the CDIL Web Site/CD are believed to be accurate and reliable. CDIL however, does not assume responsibility for inaccuracies or incomplete information. Furthermore, CDIL does not assume liability whatsoever, arising out of the application or use of any CDIL product; neither does it convey any license under its patent rights nor rights of others. These products are not designed for use in life saving/support appliances or systems. CDIL customers selling these products (either as individual Semiconductor Devices or incorporated in their end products), in any life saving/support appliances or systems or applications do so at their own risk and CDIL will not be responsible for any damages resulting from such sale(s).

CDIL strives for continuous improvement and reserves the right to change the specifications of its products without prior notice.



CDIL is a registered trademark of
Continental Device India Pvt. Limited
C-120 Narration Industrial Area, New Delhi 110 028, India.
Telephone +91-11-2579 6150, 4141 1112 Fax +91-11-2579 5290, 4141 1119
email@cdil.com www.cdil.com
CIN No. U32109DL1964PTC004291